

**ELECTROCONDUCTIVE ADHESIVE COMPOSITION, ELECTROCONDUCTIVE ADHESIVE SHEET, ELECTROMAGNETIC SHIELDING MATERIAL AND FLEXIBLE PRINTED CIRCUIT BOARD USING THE SAME**

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**Classification:**

**- international:** C09J109/02; C09J7/00; C09J9/02; C09J161/06; H01B1/20; H01B5/16; H05K3/32; H05K9/00

**- european:**

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**Abstract of JP2001207143**

**PROBLEM TO BE SOLVED:** To provide an electroconductive adhesive composition and an electroconductive adhesive sheet each having both flexibility and breaking resistance suitable for electromagnetically shielding flexible printed circuit boards (FPC), and to provide an electromagnetic shielding material composed integrally of the composition or sheet and electroconductive fiber sheet or metallic foil and imparted with flame retardancy as well.

**SOLUTION:** This electroconductive adhesive composition is obtained by incorporating an electroconductive additive composition comprising (a) an acrylonitrile-butadiene copolymer, (b) a phenolic resin and (c) an electroconductive filler with (d) a tetrabromobisphenol A derivative. The 2nd objective adhesive sheet and electromagnetic shielding material each using the above composition are provided. The 3rd objective flexible printed circuit boards (FPC) each laminated with the above electromagnetic shielding material is provided.